



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #16790JGeneric Copy

Issue Date: 09-Sep-2014**TITLE:** Initial PCN wafer fab transfer from Gifu in Japan to Niigata in Japan.**PROPOSED FIRST SHIP DATE:** starting 09-Jan-2015 until 26-Mar-2015 (the actual ship date will be different by each product, please check the responsible Sales person).**AFFECTED CHANGE CATEGORY(S):** Wafer Fabrication Site Addition**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or <Yasuhiro.Igarashi@onsemi.com>**NOTIFICATION TYPE:**

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

This is an Initial Process Change Notification to announce about expanding from conventional Manufacturers UMC to newly wafer fabrication site. Additional fabrication site is ON Semiconductor Niigata Co., Ltd. (OSNC). OSNC is located in Niigata, Japan, obtained ISO9001 certification.

The product design and electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed for each product to check the device functionality and electrical specifications. Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.


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QUALIFICATION PLAN:

Reliability Test was planned as below. Reliability Test Results will be provided in the FPCN.

Reliability Test Plan

Test Items	Test Condition	Test Time	
High Temperature Storage	Tstg max	1000	h
Temperature Humidity Storage	Ta=85°C,RH=85%	1000	h
Steady State Operating Life	Tch,Tjmax	1000	h
High Temperature Revers Bias	Tstg rmax,(VDSSmax,VCEsmax,VRmax)	1000	h
Temperature Cycle	Ta=Tstg min to max,30min each	200	Cycle
Pressure Cooker (Autoclave)	Ta=121degC,RH=100%,2.03×10 ⁵ Pa	60	h
Soldering Test	260degC,10s(Soldering bath)	1	time

Notice)

List of affected General parts:

ATP101-TL-H
ATP101-V-TL-H
ATP106-TL-H
ATP108-TL-H
ATP112-TL-H
ATP114-TL-H
ATP202-TL-H
ATP301-TL-H
ATP302-TL-H
ATP304-TL-H
ATP404-TL-H
ATP404-H-TL-H